

Pending Claims:

Following is a complete listing of the claims pending in the application:

1-6. (Canceled)

7. (Previously presented) A planarizing machine, comprising:
a table having a support surface;
a processing pad on the support surface;
a carrier assembly having a head configured to hold a microelectronic workpiece
and a drive assembly carrying the head relative to the support surface;
and
a solution dispenser separate from the head, the solution dispenser being
configured to discharge a planarizing solution onto a plurality of locations
on the pad, wherein the solution dispenser comprises: an elongated
support extending over the pad at a location spaced apart from a travel
path of the head; a fluid passageway carried by the support through which
a planarizing solution can flow; and a fluid discharge unit slidably carried
by the support and in fluid communication with the fluid passageway, the
fluid discharge unit being moveable along the support to discharge a flow
of the planarizing solution onto separate areas of the processing pad.

8. (Previously presented) A planarizing machine, comprising:
a table having a support surface;
a processing pad on the support surface;
a carrier assembly having a head configured to hold a microelectronic workpiece
and a drive assembly carrying the head relative to the support surface;
and
a solution dispenser separate from the head, the solution dispenser being
configured to discharge a planarizing solution onto a plurality of locations
on the pad, wherein the solution dispenser comprises a support extending

over the pad at a location spaced apart from a travel path of the head, a fluid passageway carried by the support through which a planarizing solution can flow, and a nozzle carried by the support and in fluid communication with the fluid passageway, the nozzle being rotatably coupled to the support.

9-17. (Canceled)

18. (Previously presented) A planarizing machine, comprising:
a table having a support surface;
a processing pad on the support surface;
a carrier assembly having a head configured to hold a microelectronic workpiece and a drive assembly carrying the head; and
a solution dispenser separate from the head, the solution dispenser having a support extending over the pad and a distributor carried by the support, the distributor being configured to discharge a planarizing solution from a plurality of locations along the support, wherein the support comprises an elongated arm and a fluid passageway carried by the arm through which a planarizing solution can flow, and the distributor further comprises a fluid discharge unit slidably carried by the arm and in fluid communication with the fluid passageway, the fluid discharge unit being moveable along the arm to discharge a flow of the planarizing solution along different areas of the processing pad.

19. (Previously presented) A planarizing machine, comprising:
a table having a support surface;
a processing pad on the support surface;
a carrier assembly having a head configured to hold a microelectronic workpiece and a drive assembly carrying the head; and
a solution dispenser separate from the head, the solution dispenser having a support extending over the pad and a distributor carried by the support,

the distributor being configured to discharge a planarizing solution from a plurality of locations along the support, wherein the support comprises an elongated arm and a fluid passageway carried by the arm through which a planarizing solution can flow, and the distributor further comprises a nozzle carried by the arm and in fluid communication with the fluid passageway, the nozzle being rotatably coupled to the arm.

20. (Original) A planarizing machine, comprising:

a table having a support surface;
a processing pad on the support surface;
a carrier assembly having a head configured to hold a microelectronic workpiece and a drive assembly carrying the head; and
a solution dispenser having support above the pad and a nozzle moveably coupled to the support, the nozzle being coupleable to a planarizing solution.

21. (Original) The planarizing machine of claim 20 wherein:

the support comprises an elongated arm and a fluid passageway carried by the arm through which a planarizing solution can flow; and
the nozzle is slidably carried by the arm and in fluid communication with the fluid passageway.

22. (Original) The planarizing machine of claim 20 wherein:

the support comprises an elongated arm and a fluid passageway carried by the arm through which a planarizing solution can flow; and
the nozzle is rotatably coupled to the arm.

23-51. (Canceled)

52. (Previously presented) A method of processing a microelectronic workpiece, comprising:

removing material from the workpiece by pressing the workpiece against a contact surface of a processing pad and imparting relative motion between the workpiece and the contact surface; and

discharging a planarizing solution directly onto a first region of the contact surface and concurrently discharging the planarizing solution directly onto a second region of the contact surface separate from the first region, the planarizing solution being deposited onto the first and second regions separate from a head carrying the workpiece, wherein discharging the planarizing solution comprises (a) passing the planarizing solution through a fluid discharge unit that is moveably carried by a support over the processing pad and (b) concurrently moving the fluid discharge unit relative to the support to discharge the planarizing fluid at different regions across the contact surface.

53. (Original) The method of claim 52 wherein moving the fluid discharge unit comprises sliding the fluid discharge unit along the support.

54. (Original) The method of claim 52 wherein moving the fluid discharge unit comprises rotating the fluid discharge unit about a pivot point on the support.

55. (Canceled)